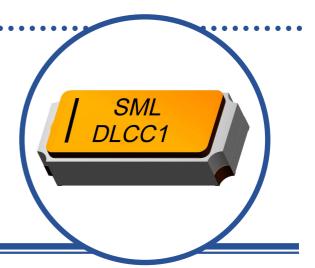
DIODE LEADLESS CHIP CARRIER



DLCC1

- Light Weight Hermetic Ceramic Surface Mount Package is designed as a drop In replacement for "MELF-4.5 (D-5D)"/ "DO-213AA" Packages
- Designed For High Reliability Military, Aerospace and Space Applications



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25$ °C unless otherwise stated)

V _{RMS}	Maximum RMS Voltage	>700V
V_{DC}	Maximum DC Blocking Voltage	>1000V
1	Maximum DC Output Current	1.0A

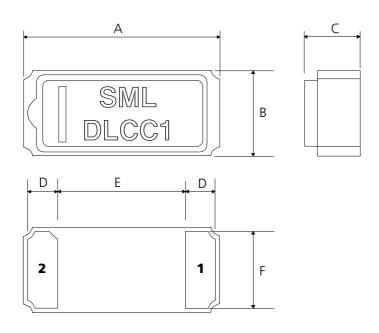
PACKAGE MASS

63Sn/37Pb Solder Tin Dipped typically <40mg

Comparisons with similar DO-213AA packages shows no increase in weight:

1N750AUR-1 = 40mg1N4620UR-1 = 40mg

MECHANICAL DATA



DLCC1 Variant A (D1A)

PAD 1	ANODE			
PAD 2	CATHODE			
·				
DIMENSION	mm	Inches		
А	4.60 ±0.20	0.181 ±0.007		
В	2.00 ±0.20	0.079 ±0.007		
C	1.30 ±0.20	0.051 ±0.007		
D	0.70 ±0.20	0.028 ±0.007		
E	3.00 ±0.20	0.118 ±0.007		
F	1.80 ±0.20	0.071 ±0.007		

Semelab Ltd reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing an order.



DIODE LEADLESS CHIP CARRIER DLCC1



DLCC1 PCB SOLDER PAD LAYOUT GUIDE

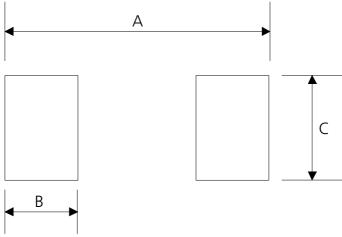
The DLCC1 package is designed to align conveniently with the industry standard pad layouts (See Below) for the "MELF-4.5 (D 5D)" and DO-213AA packages.

The design allows easy substitution of the DLCC1 package into existing board designs providing easy surface mount process integration, excellent cost and availability benefits over MELF packages.

Soldering temperature should be 260°C for a maximum of 10 seconds.

The DLCC1 pad castellations allows solder flow up the sides of the package enabling visual inspection of the

successful solder joint.



DO-213AA SOLDER PADS

DIMENSION	mm	Inches
А	5.08	0.200
В	1.40	0.055
С	2.03	0.080

MELF-4.5 (D-5D) SOLDER PADS

DIMENSION	mm	Inches
А	6.45	0.254
В	1.70	0.067
С	2.41	0.095



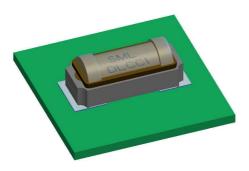


Image Showing the DLCC1 on the recommended DO-213AA solder pad foot print and DO-213AA package overlay.



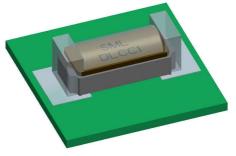


Image Showing the DLCC1 on the recommended MELF-4.5 (D-5D) solder pad foot print and MELF-4.5 (D-5D) package overlay.

DIODE LEADLESS CHIP CARRIER

Telectronics Semelab Limited

SCREENING OPTIONS

Space Level (JQRS/ESA) and High Reliability options are available in accordance with the <u>High Reliability and Screening Options Handbook</u> available for download from the from the TT electronics Semelab web site.

ESA Quality Level Products are based on the testing procedures specified in the generic ESCC 5000 and in the corresponding part detail specifications.

Semelab's QR216 and QR217 processing specifications (JQRS), in conjunction with the companies ISO 9001:2000 approval present a viable alternative to the American MIL-PRF-19500 space level processing.

QR217 (Space Level Quality Conformance) is based on the quality conformance inspection requirements of MIL-PRF-19500 groups A (table V), B (table VIa), C (table VII) and also ESA / ESCC 5000 (chart F4) lot validation tests.

QR216 (Space Level Screening) is based on the screening requirements of MIL-PRF-19500 (table IV) and also ESA /ESCC 5000 (chart F3).

JQRS parts are processed to the device data sheet and screened to QR216 with conformance testing to Q217 groups A and B in accordance with MIL-STD-750 methods and procedures.

Additional conformance options are available, for example Pre-Cap Visual Inspection, Buy-Off Visit or Data Packs. These are chargeable and must be specified at the order stage (See Ordering Information). Minimum order quantities may apply.

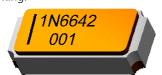
Alternative or additional customer specific conformance or screening requirements would be considered. Contact Semelab sales with enquires.

MARKING DETAILS

Parts can be laser marked with approximately 7 characters on two lines and always includes cathode identification. Typical marking would include part or specification number, week of seal or serial number subject to available space and legibility.

Customer specific marking requirements can be arranged at the time of order.

Example Marking:



ORDERING INFORMATION

Part numbers are built up from Type, Package Variant, and screening level. The part numbers are extended to include the additional options as shown below.

Type – See Electrical Stability Characteristics Table Package Variant – See Mechanical Data Screening Level – See Screening Options (ESA / JQRS)

Additional Options:

.CVP
.CVB
.DA
.SS
.SEM
.XRAY
.RAD
.GRPB
.GBDM (12 pieces)
.GRPC
.GCDE (12 pieces)
.GCDM (6 pieces)
.LVT1
.L1DE (15 pieces)
.L1DM (15 pieces)
.LVT2
.L2D (15 pieces)
.LVT3
.L3D (5 pieces)

Additional Option Notes:

- 1) All 'Additional Options' are chargeable and must be specified at order stage.
- When Group B,C or LVT is required, additional electrical and mechanical destructive samples must be ordered
- 3) All destructive samples are marked the same as other production parts unless otherwise requested.

Example ordering information:

The following example is for the 1N6642 part with package variant A, JQRS screening, additional Group C conformance testing and a Data pack.

Part Numbers:

1N6642D1A-JQRS (Include quantity for flight parts)
1N6642D1A-JQRS.GRPC (chargeable conformance option)
1N6642D1A-JQRS.GCDE (charge for destructive parts)
1N6642D1A-JQRS.GCDM (charge for destructive parts)
1N6642D1A-JQRS.DA (charge for Data pack)

Customers with any specific requirements (e.g. marking or screening) may be supplied with a similar alternative part number (there is maximum 20 character limit to part numbers). Contact Semelab sales with enquiries

High Reliability and Screening Options Handbook link: http://www.semelab.co.uk/pdf/misc/documents/hirel_and_screening_options.pdf

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Website: http://www.semelab-tt.com



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